



US00D909979S

(12) **United States Design Patent** (10) **Patent No.:** **US D909,979 S**  
**Tseng et al.** (45) **Date of Patent:** **\*\* Feb. 9, 2021**

(54) **VAPOR CHAMBER**

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(\*\*) Term: **15 Years**

(21) Appl. No.: **29/627,535**

(22) Filed: **Nov. 28, 2017**

(51) **LOC (13) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/179**

(58) **Field of Classification Search**  
USPC ..... D13/179  
CPC .... F28D 15/046; F28D 15/0233; F28D 15/00;  
F28D 15/02

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a vapor chamber, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a first embodiment of a vapor chamber showing the new design;

FIG. 2 is a front elevational view thereof, the rear elevational view being omitted;

FIG. 3 is a right side elevational view thereof, the left side elevational view being omitted;

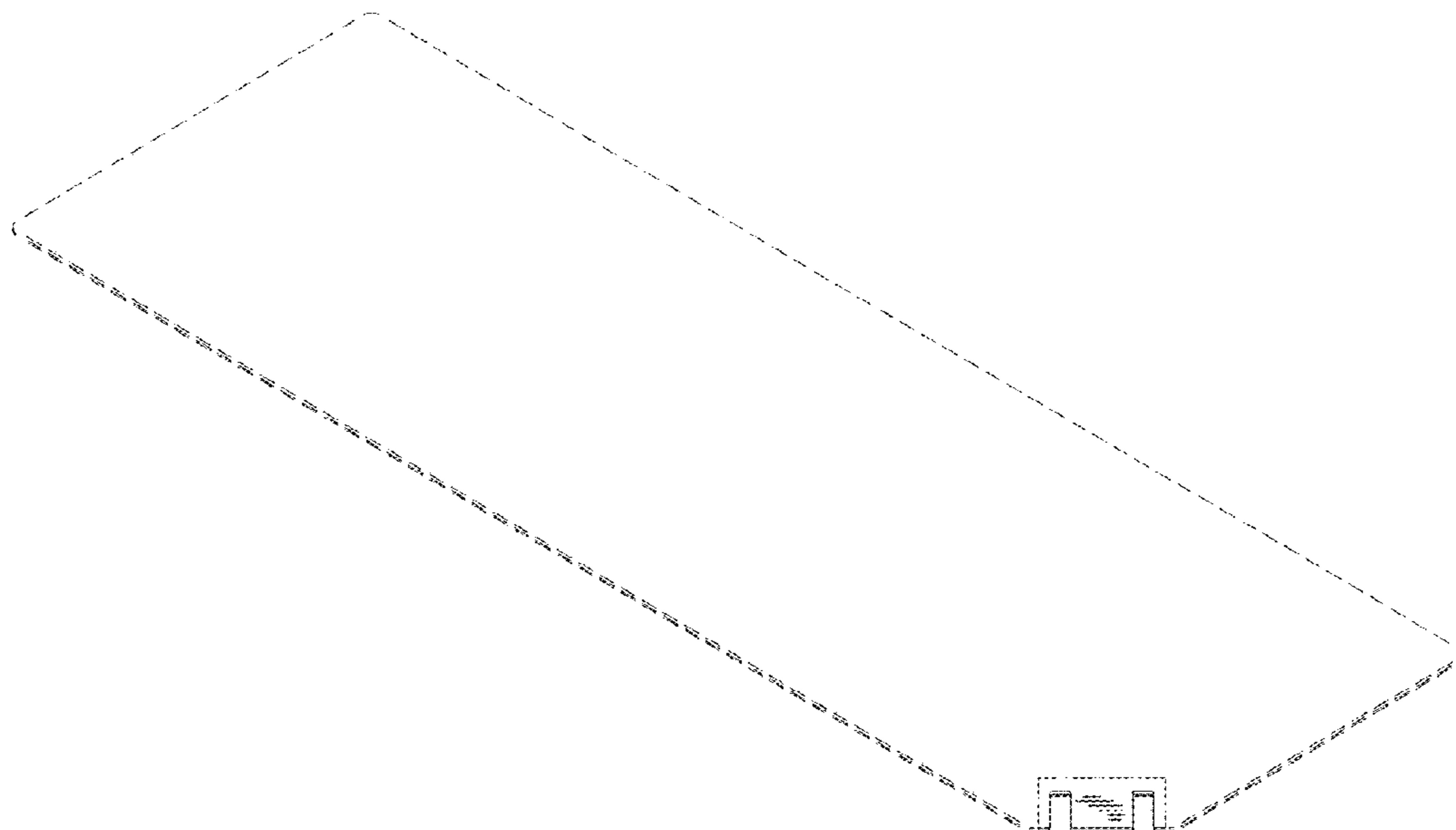
FIG. 4 is a top plan view thereof;

FIG. 5 is a bottom plan view thereof; and,

FIG. 6 is a perspective view of a second embodiment of a vapor chamber showing the new design.

The broken lines shown in FIGS. 1-6 depict portions of the vapor chamber that form no part of the claimed design. The dash-dot-dash line drawn in the FIGS. 1-6 depict boundary of the claimed design.

**1 Claim, 6 Drawing Sheets**



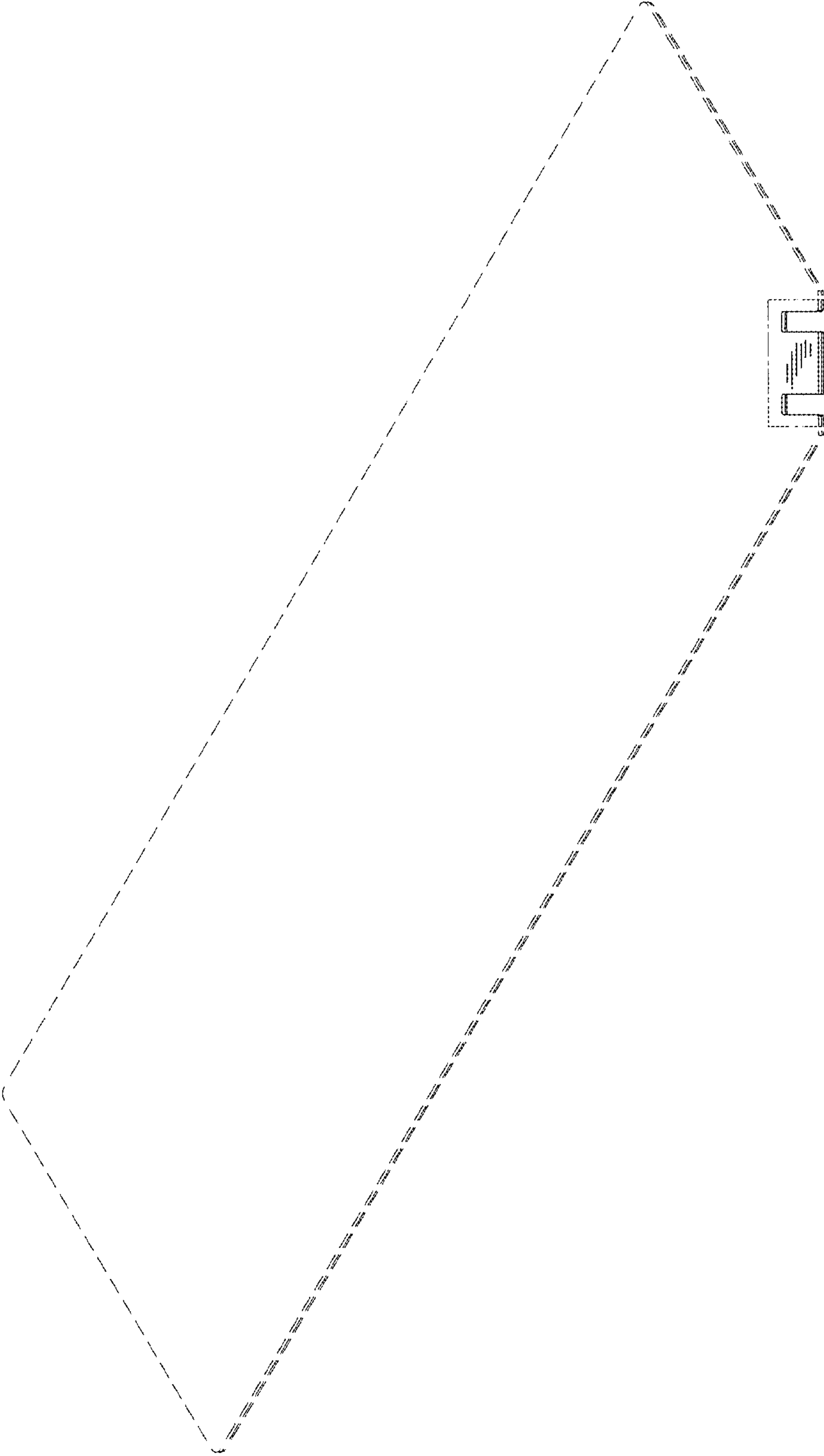


FIG. 1

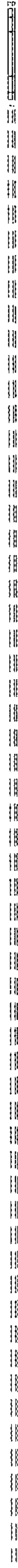


FIG. 2

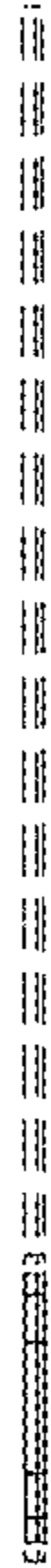


FIG. 3

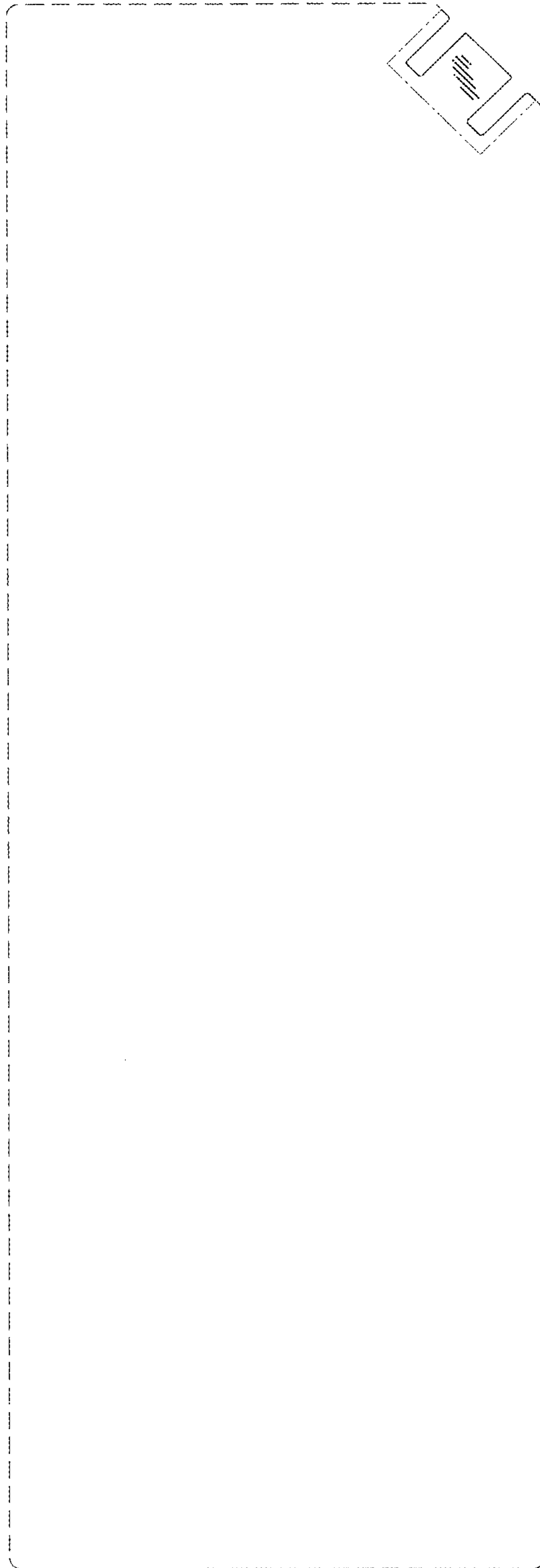


FIG. 4

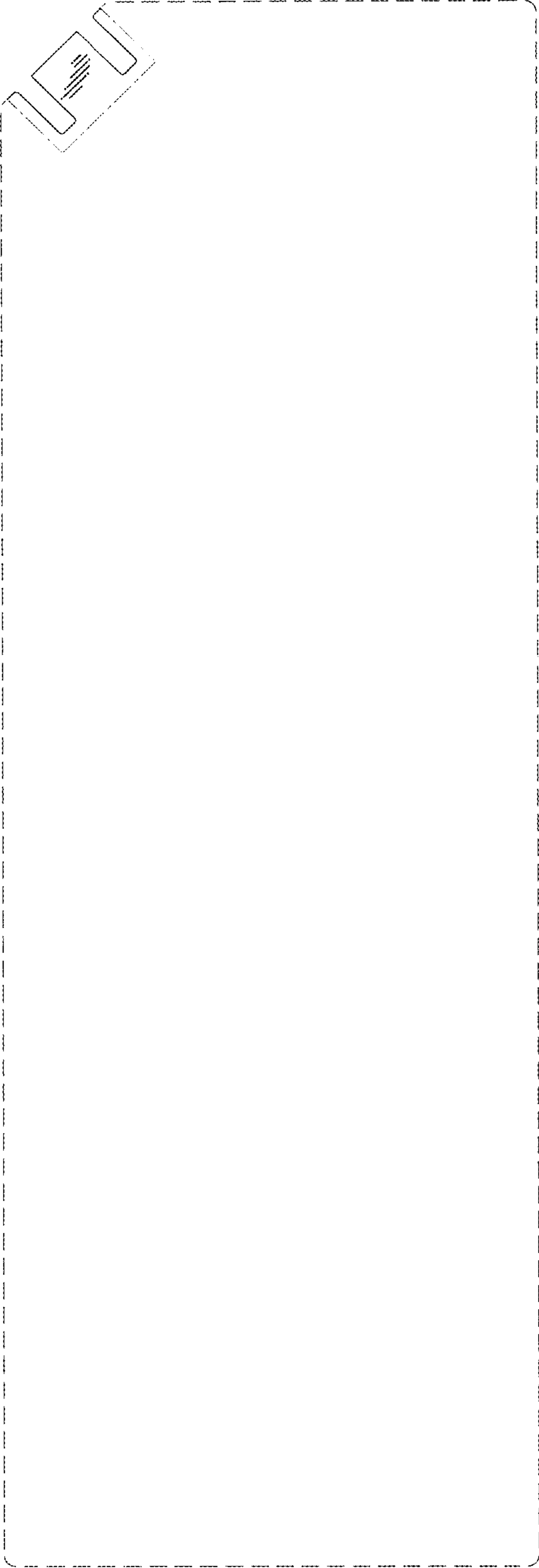


FIG. 5

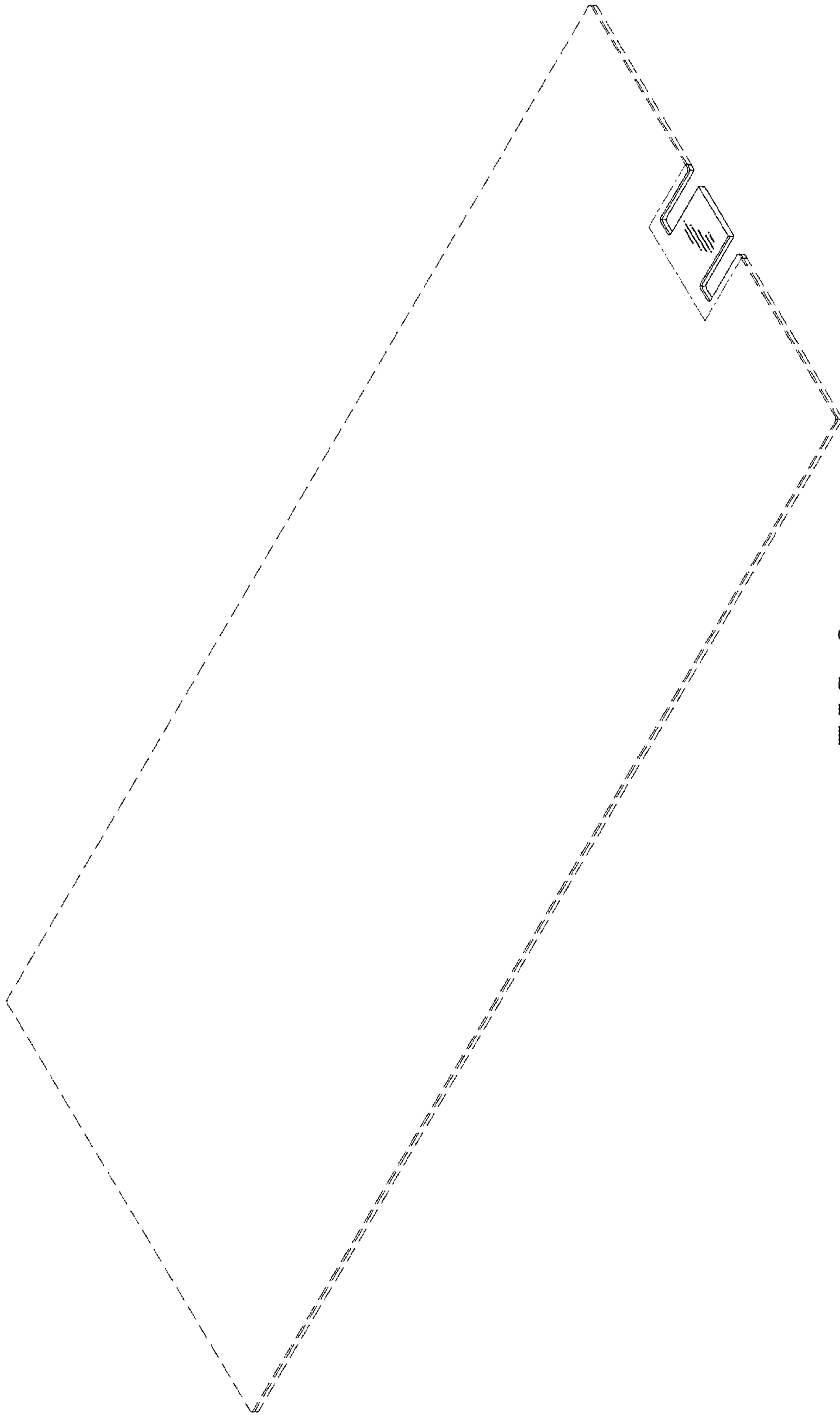


FIG. 6